

SUNRIDGE

PLCC-L SERIES

PLCC SOCKET, OPEN FRAME, LOW PROFILE, SURFACE MOUNT

PRODUCT FEATURES:

- Ultra low profile: .168" overall height
- Condensed overall dimension: Accommodate demanding requirement of high density and space premium of contemporary electronics packaging.
- Stringently controlled .004" max coplanarity: Ensure solid solder joint to PCB.
- Solder lead configuration to allow even flow solder paste: Assurance of "never short circuit" of adjacent trace or component, even in over-populated PCB layout.
- Open frame housing with thin-tipped solder lead: Ease of inspectability and repairability of lead-to-PCB pad solder joint.
- Same footprint as standard PCB solder pad layout for PLCC chip per JEDEC specifications.
- Housing rigidly constructed with high temperature resistant resin to sustain thermal requirement of reflow process. Smooth surfaced center pad of true flatness facilitates automatic vacuum pick and placement process.
- Optimally engineered spring load contact design: Low insertion force, with rigid and stable engagement with PLCC chip.
- Reinforced tube packaging: Designed to en-capsule the sockets in parallel position without direct contact to the sensible solder leads, as a cost effective means, to adapt to stick feeder mechanism of pick & placement machines, and to maintain the integrity of lead coplanarity during handling .
- Packaging in tape and reel, per industries standard ANSI/EIA -481 -1 & -481 -2, or other formats available, as user's option.

MATERIAL:

Contact Material: Phosphor bronze, Tin Plated

Insulator Material: Polyphenylene sulfide, UL 94V-0

PERFORMANCE CHARACTERISTICS:

Durability: Per MIL-STD-1344, 100 cycles

Vibration: Per MIL-STD-810C, 10-20,000 HZ, 5 Gs

Shock: Per- MIL-STD-810C, 35 Gs

Contact Interface Resistance: Initial: 6.5 milliohms average
Final: 15.0 milliohms maximum after testing

Insulation Resistance: Greater than 1 x 10 megohms

Dielectrical Strength: 1000VAC for 1 minute

Capacitance: Less than 1.0 pF at 1,000 Hz

Inductance: Self: 5.0 nH, maximum at 500 KHz

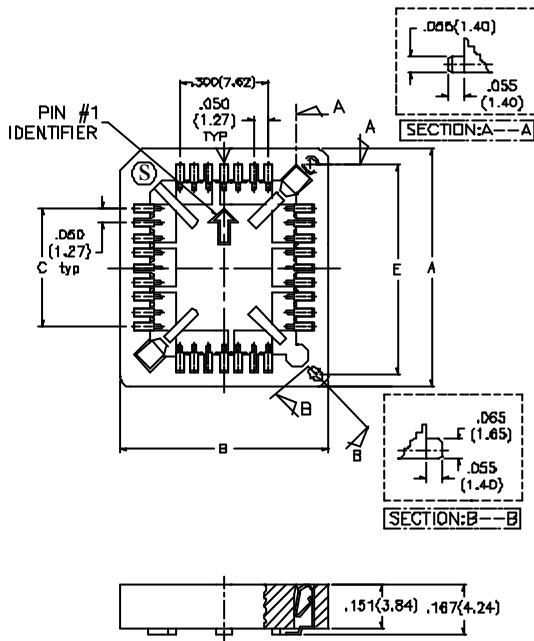
Mutual: 1.0 nH, maximum at 500 KHz

Thermal Shock: Per MIL-STD-1344, condition A, cycled from -55 to + 85 , no discontinuity or physical damage

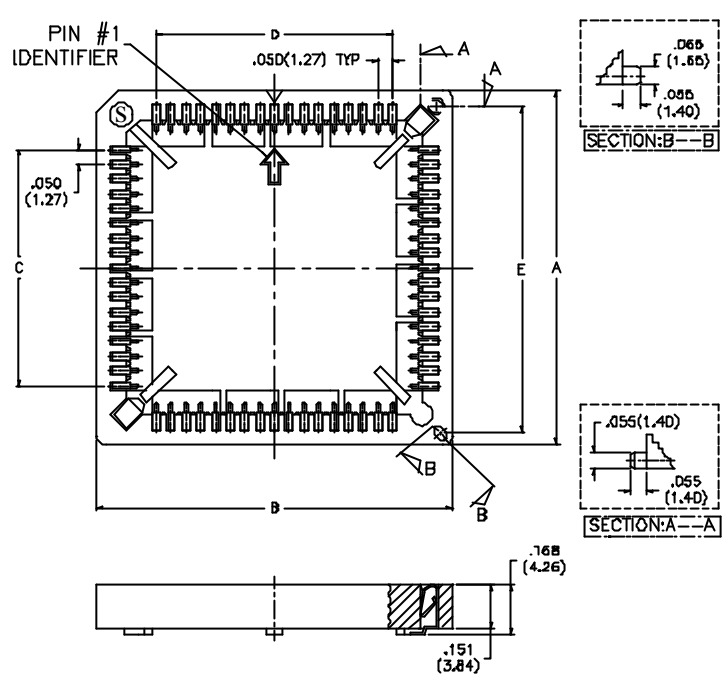
Temperature/Humidity: Per MIL-STD-1344, 85 C/85% relative humidity

Operating Temperature: -50 to +105

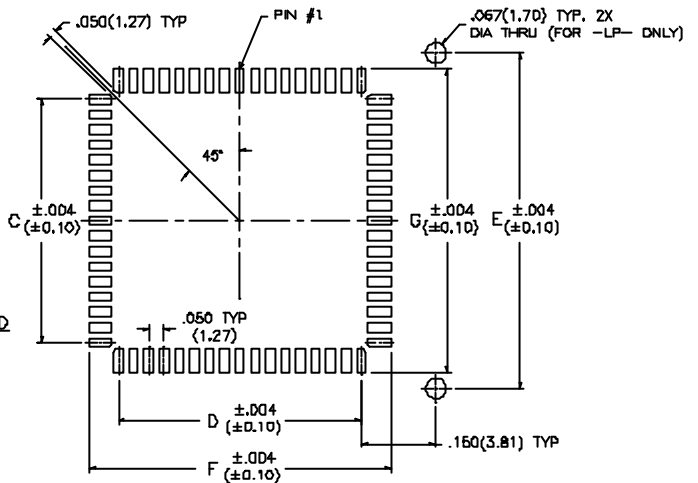
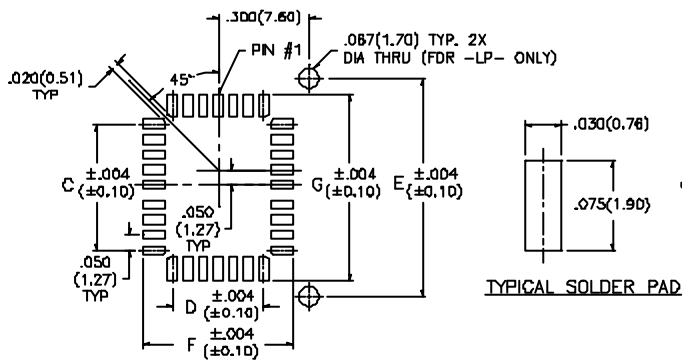
SUNRIDGE



32P SOCKET SHOE



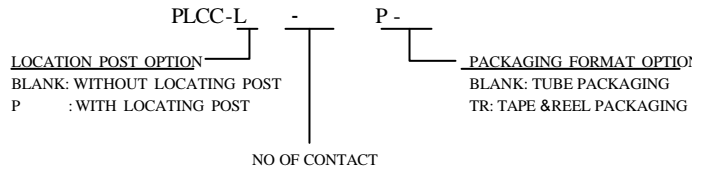
68P SOCKET SHOE



RECOMMENDED PCB PAD LAYOUT

NO. OF POS.	A	B	C	D	E	F	G
20	.585 (14.86)	.585 (14.86)	.200 (5.08)	.200 (5.08)	.500 (12.70)	.395 (10.03)	.395 (10.03)
28	.685 (17.40)	.685 (17.40)	.300 (7.62)	.300 (7.62)	.600 (15.24)	.495 (12.57)	.495 (12.57)
32	.766 (19.45)	.665 (16.90)	.400 (10.16)	.300 (7.62)	.700 (17.78)	.495 (12.57)	.595 (15.11)
44	.885 (22.48)	.885 (22.48)	.500 (12.70)	.500 (12.70)	.800 (20.32)	.695 (17.65)	.695 (17.65)
52	1.000 (25.40)	1.000 (25.40)	.600 (15.24)	.600 (15.25)	.900 (22.86)	.795 (20.19)	.795 (20.19)
68	1.202 (30.54)	1.202 (30.54)	.800 (20.32)	.800 (20.32)	1.100 (27.94)	.995 (25.27)	.995 (25.27)
84	1.400 (35.56)	1.400 (35.56)	1.000 (25.40)	1.000 (25.40)	1.300 (33.02)	1.195 (30.35)	1.195 (30.35)

P/N DESIGNATION



EXAMPLE:
 32P, WITHOUT POST, TAPE & REEL PACKAGED, P/N PLCC -L-32P-TR
 68P, WITH POST, TUBE PACKAGED, P/N PLCC -LP-68P